

WHAT IS CLAIMED IS:

1. An electronic apparatus comprising:

an electronic circuit board;

an electrically conductive casing for encasing said electronic circuit board;

a semiconductor element module electrically connected to said electronic circuit board; and

a resin fixture intervening between said electrically conductive casing and said semiconductor element module, said resin fixture mounted with said semiconductor element module and fitted to said electrically conductive casing.

2. An electronic apparatus according to claim 1, wherein

said resin fixture has a notched portion formed in its outer wall, and wherein

said electrically conductive casing has a hooked portion which fits said notched portion.

3. An electronic apparatus according to claim 1, wherein

said resin fixture has a protrusion formed on its outer wall, and wherein

said electrically conductive casing has an insertion aperture for receiving said protrusion.

4. An electronic apparatus according to claim 1, wherein

said semiconductor element module has a raised portion formed

on its outer surface at a site where said semiconductor element module is fitted to said resin fixture, and wherein

said resin fixture has a recessed portion formed in its inner surface at a site where said semiconductor module is mounted, said

5 recessed portion being fitted to said raised portion.

5. An electronic apparatus according to claim 1, wherein

said semiconductor element module has an externally threaded portion formed on its outer surface at a site where said

10 semiconductor element module is fitted to said resin fixture, and wherein

said resin fixture has an internally threaded portion formed in its inner surface at a site where said semiconductor module is mounted, said externally threaded portion being screwed into said

15 internally threaded portion.

6. An electronic apparatus according to claim 1, wherein

said semiconductor element module has a recessed portion formed in its outer surface at a site where said semiconductor

20 element module is fitted to said resin fixture, and wherein

said resin fixture has a raised portion formed on its inner surface at a site where said semiconductor module is mounted, said raised portion being fitted to said recessed portion.

25 7. An electronic apparatus according to claim 1, wherein

said resin fixture has a metal-plated outer surface.

8. An electronic apparatus according to claim 1, wherein
said electronic circuit board is bonded to and encased in
said electrically conductive casing by use of an electrically
conductive adhesive sheet.

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9. An electronic apparatus according to claim 1, wherein
said semiconductor element module is an optical
semiconductor element module.

10 10. An electronic apparatus according to claim 1, wherein
said semiconductor element module has a raised portion formed
on its outer surface at a site where said semiconductor element
module is fitted to said resin fixture, and wherein

15 said resin fixture has a notched portion formed in its outer
wall and has a recessed portion formed in the inner surface at a
site where said semiconductor module is mounted, said recessed
portion being fitted to said raised portion, and wherein

said electrically conductive casing has a hooked portion
which fits said notched portion of said resin fixture.

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11. An electronic apparatus according to claim 1, wherein
said semiconductor element module has an externally threaded
portion formed on its outer surface at a site where said
semiconductor element module is fitted to said resin fixture, and

25 wherein

said resin fixture has a notched portion formed in its outer
wall and has an internally threaded portion formed in its inner

surface at a site where said semiconductor module is mounted, said externally threaded portion being screwed into said internally threaded portion, and wherein

said electrically conductive casing has a hooked portion
5 which fits said notched portion of said resin fixture.

12. An electronic apparatus according to claim 1, wherein

said semiconductor element module has a recessed portion formed in its outer surface at a site where said semiconductor
10 element module is fitted to said resin fixture, and wherein

said resin fixture has a notched portion formed in its outer wall and has a raised portion formed on its inner surface at a site where said semiconductor module is mounted, said raised portion being fitted to said recessed portion, and wherein

15 said electrically conductive casing has a hooked portion which fits said notched portion of said resin fixture.

13. An electronic apparatus according to claim 1, wherein

said semiconductor element module has a raised portion formed
20 on its outer surface at a site where said semiconductor element module is fitted to said resin fixture, and wherein

said resin fixture has a protrusion formed on its outer surface and has a recessed portion formed in its inner surface at a site where said semiconductor module is mounted, said recessed
25 portion being fitted to said raised portion, and wherein

said electrically conductive casing has an insertion hole which receives said protrusion of said resin fixture.

14. An electronic apparatus according to claim 1, wherein
said semiconductor element module has an externally threaded
portion formed on its outer surface at a site where said
5 semiconductor element module is fitted to said resin fixture, and
wherein

said resin fixture has a protrusion formed on its outer
surface and has an internally threaded portion formed in its inner
surface at a site where said semiconductor module is mounted, said
10 externally threaded portion being screwed into said internally
threaded portion, and wherein

said electrically conductive casing has an insertion hole
which receives said protrusion of said resin fixture.

15 15. An electronic apparatus according to claim 1, wherein
said semiconductor element module has a recessed portion
formed in its outer surface at a site where said semiconductor
element module is fitted to said resin fixture, and wherein

said resin fixture has a protrusion formed on its outer
20 surface and has a raised portion formed on its inner surface at
a site where said semiconductor module is mounted, said raised
portion being fitted to said recessed portion, and wherein

said electrically conductive casing has an insertion hole
which receives said protrusion of said resin fixture.

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16. An electronic apparatus according to claim 1, wherein
said resin fixture has a notched portion formed in its outer

wall and has a protrusion formed on its outer surface, and wherein
said electrically conductive casing has a hooked portion
which fits said notched portion and with an insertion hole which
receives said protrusion.

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17. An electronic apparatus according to claim 1, wherein
said semiconductor element module has a raised portion formed
on its outer surface at a site where said semiconductor element
module is fitted to said resin fixture, and wherein

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said resin fixture has a notched portion formed in its outer
wall and a protrusion formed on its outer surface and has a recessed
portion formed in the inner surface at a site where said
semiconductor module is mounted, said recessed portion being fitted
to said raised portion, and wherein

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said electrically conductive casing has a hooked portion
which fits said notched portion of said resin fixture and an
insertion hole which receives said protrusion of said resin
fixture.

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18. An electronic apparatus according to claim 1, wherein
said semiconductor element module has an externally threaded
portion formed on its outer surface at a site where said
semiconductor element module is fitted to said resin fixture, and
wherein

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said resin fixture has a notched portion formed in its outer
wall and a protrusion formed on its outer surface and has an
internally threaded portion formed in the inner surface at a site

where said semiconductor module is mounted, said externally threaded portion being screwed into said internally threaded portion, and wherein

5 said electrically conductive casing has a hooked portion which fits said notched portion of said resin fixture and an insertion hole which receives said protrusion of said resin fixture.

19. An electronic apparatus according to claim 1, wherein
10 said semiconductor element module has a recessed portion formed in its outer surface at a site where said semiconductor element module is fitted to said resin fixture, and wherein

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15 said resin fixture has a notched portion formed in its outer wall and a protrusion formed on its outer surface and has a raised portion formed on its inner surface at a site where said semiconductor module is mounted, said raised portion being fitted to said recessed portion, and wherein

20 said electrically conductive casing has a hooked portion which fits said notched portion of said resin fixture and with an insertion hole which receives said protrusion of said resin fixture.